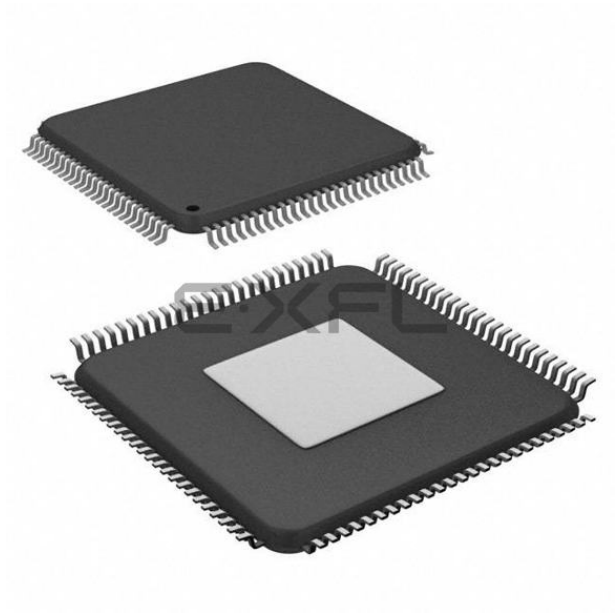
Infineon Technologies - XC2268N40F80LAAKXUMA1 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166SV2
Core Size	16/32-Bit
Speed	80MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I²S, POR, PWM, WDT
Number of I/O	76
Program Memory Size	320KB (320K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	42K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-8
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc2268n40f80laakxuma1

Ordering Information

The ordering code for an Infineon microcontroller provides an exact reference to a specific product. This ordering code identifies:

- the derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the temperature range:
  - SAF-…: -40°C to 85°C
  - SAH-…: -40°C to 110°C
  - SAK-…: -40°C to 125°C
- the package and the type of delivery.

For ordering codes for the XC226xN please contact your sales representative or local distributor.

This document describes several derivatives of the XC226xN group:

Basic Device Types are readily available and
Special Device Types are only available on request.

As this document refers to all of these derivatives, some descriptions may not apply to a specific product, in particular to the special device types.

For simplicity the term **XC226xN** is used for all derivatives throughout this document.

1.1 Basic Device Types

Basic device types are available and can be ordered through Infineon's direct and/or distribution channels.

Table 1 Synopsis of XC226xN Basic Device Types

Derivative[1]	Flash Memory[2]	PSRAM DSRAM[3]	Capt./Comp. Modules	ADC[4] Chan.	Interfaces[4]
XC2268N-40FxLR	320 Kbytes	16 Kbytes 16 Kbytes	CC2 CCU60/1	11 + 5	6 CAN Nodes, 6 Serial Chan.

1) x is a placeholder for available speed grade in MHz.

2) Specific information about the on-chip Flash memory in **Table 3**.

3) All derivatives additionally provide 8 Kbytes SBRAM and 2 Kbytes DPRAM.

4) Specific information about the available channels in **Table 5**.
Analog input channels are listed for each Analog/Digital Converter module separately (ADC0 + ADC1).

1.2 Special Device Types

Special device types are only available for high-volume applications on request.

Table 2 Synopsis of XC226xN Special Device Types

Derivative[1]	Flash Memory[2]	PSRAM DSRAM[3]	Capt./Comp. Modules	ADC[4] Chan.	Interfaces[4]
XC2261N-24FxL	192 Kbytes	4 Kbytes 4 Kbytes	CC2 CCU60/1	11 + 0	1 CAN Node, 2 Serial Chan.
XC2263N-16FxL	128 Kbytes	4 Kbytes 4 Kbytes	CC2 CCU60/1	11 + 5	1 CAN Node, 4 Serial Chan.
XC2263N-24FxL	192 Kbytes	8 Kbytes 8 Kbytes	CC2 CCU60/1	11 + 5	1 CAN Node, 4 Serial Chan.
XC2263N-40FxL	320 Kbytes	8 Kbytes 16 Kbytes	CC2 CCU60/1	11 + 5	1 CAN Node, 4 Serial Chan.
XC2264N-16FxL	128 Kbytes	4 Kbytes 4 Kbytes	CC2 CCU60/1	8 + 0	2 CAN Node, 4 Serial Chan.
XC2264N-24FxL	192 Kbytes	8 Kbytes 8 Kbytes	CC2 CCU60/1	8 + 0	2 CAN Node, 4 Serial Chan.
XC2264N-40FxL	320 Kbytes	16 Kbytes 16 Kbytes	CC2 CCU60/1	8 + 0	2 CAN Node, 4 Serial Chan.
XC2265N-16FxL	128 Kbytes	4 Kbytes 4 Kbytes	CC2 CCU60/1	11 + 5	3 CAN Node, 6 Serial Chan.
XC2265N-24FxL	192 Kbytes	8 Kbytes 8 Kbytes	CC2 CCU60/1	11 + 5	3 CAN Node, 6 Serial Chan.
XC2265N-40FxL	320 Kbytes	8 Kbytes 16 Kbytes	CC2 CCU60/1	11 + 5	3 CAN Node, 6 Serial Chan.
XC2268N-40FxL	320 Kbytes	16 Kbytes 16 Kbytes	CC2 CCU60/1	11 + 5	6 CAN Nodes, 6 Serial Chan.

1) x is a placeholder for available speed grade in MHz.

2) Specific information about the on-chip Flash memory in **Table 3**.

3) All derivatives additionally provide 8 Kbytes SBRAM and 2 Kbytes DPRAM.

4) Specific information about the available channels in **Table 5**.
Analog input channels are listed for each Analog/Digital Converter module separately (ADC0 + ADC1).

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
58	P0.2	O0 / I	St/B	**Bit 2 of Port 0, General Purpose Input/Output**
	U1C0_SCLKOUT	O1	St/B	**USIC1 Channel 0 Shift Clock Output**
	TxDC0	O2	St/B	**CAN Node 0 Transmit Data Output**
	CCU61_CC62	O3	St/B	**CCU61 Channel 2 Output**
	A2	OH	St/B	**External Bus Interface Address Line 2**
	U1C0_DX1B	I	St/B	**USIC1 Channel 0 Shift Clock Input**
	CCU61_CC62INA	I	St/B	**CCU61 Channel 2 Input**
59	P10.0	O0 / I	St/B	**Bit 0 of Port 10, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	CCU60_CC60	O2	St/B	**CCU60 Channel 0 Output**
	AD0	OH / IH	St/B	**External Bus Interface Address/Data Line 0**
	CCU60_CC60INA	I	St/B	**CCU60 Channel 0 Input**
	ESR1_2	I	St/B	**ESR1 Trigger Input 2**
	U0C0_DX0A	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U0C1_DX0A	I	St/B	**USIC0 Channel 1 Shift Data Input**
60	P10.1	O0 / I	St/B	**Bit 1 of Port 10, General Purpose Input/Output**
	U0C0_DOUT	O1	St/B	**USIC0 Channel 0 Shift Data Output**
	CCU60_CC61	O2	St/B	**CCU60 Channel 1 Output**
	AD1	OH / IH	St/B	**External Bus Interface Address/Data Line 1**
	CCU60_CC61INA	I	St/B	**CCU60 Channel 1 Input**
	U0C0_DX1A	I	St/B	**USIC0 Channel 0 Shift Clock Input**
	U0C0_DX0B	I	St/B	**USIC0 Channel 0 Shift Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
65	P2.13	O0 / I	St/B	**Bit 13 of Port 2, General Purpose Input/Output**
	U2C1_SELO 2	O1	St/B	**USIC2 Channel 1 Select/Control 2 Output**
	RxDC2D	I	St/B	**CAN Node 2 Receive Data Input**
66	P2.10	O0 / I	St/B	**Bit 10 of Port 2, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	U0C0_SELO 3	O2	St/B	**USIC0 Channel 0 Select/Control 3 Output**
	CC2_CC23	O3 / I	St/B	**CAPCOM2 CC23IO Capture Inp./ Compare Out.**
	A23	OH	St/B	**External Bus Interface Address Line 23**
	U0C1_DX0E	I	St/B	**USIC0 Channel 1 Shift Data Input**
	CAPINA	I	St/B	**GPT12E Register CAPREL Capture Input**
67	P10.3	O0 / I	St/B	**Bit 3 of Port 10, General Purpose Input/Output**
	CCU60_COU T60	O2	St/B	**CCU60 Channel 0 Output**
	AD3	OH / IH	St/B	**External Bus Interface Address/Data Line 3**
	U0C0_DX2A	I	St/B	**USIC0 Channel 0 Shift Control Input**
	U0C1_DX2A	I	St/B	**USIC0 Channel 1 Shift Control Input**
68	P0.5	O0 / I	St/B	**Bit 5 of Port 0, General Purpose Input/Output**
	U1C1_SCLK OUT	O1	St/B	**USIC1 Channel 1 Shift Clock Output**
	U1C0_SELO 2	O2	St/B	**USIC1 Channel 0 Select/Control 2 Output**
	CCU61_COU T62	O3	St/B	**CCU61 Channel 2 Output**
	A5	OH	St/B	**External Bus Interface Address Line 5**
	U1C1_DX1A	I	St/B	**USIC1 Channel 1 Shift Clock Input**
	U1C0_DX1C	I	St/B	**USIC1 Channel 0 Shift Clock Input**
	RXDC3E	I	St/B	**CAN Node 3 Receive Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
69	P10.4	O0 / I	St/B	**Bit 4 of Port 10, General Purpose Input/Output**
	U0C0_SELO 3	O1	St/B	**USIC0 Channel 0 Select/Control 3 Output**
	CCU60_COU T61	O2	St/B	**CCU60 Channel 1 Output**
	AD4	OH / IH	St/B	**External Bus Interface Address/Data Line 4**
	U0C0_DX2B	I	St/B	**USIC0 Channel 0 Shift Control Input**
	U0C1_DX2B	I	St/B	**USIC0 Channel 1 Shift Control Input**
	ESR1_9	I	St/B	**ESR1 Trigger Input 9**
70	P10.5	O0 / I	St/B	**Bit 5 of Port 10, General Purpose Input/Output**
	U0C1_SCLK OUT	O1	St/B	**USIC0 Channel 1 Shift Clock Output**
	CCU60_COU T62	O2	St/B	**CCU60 Channel 2 Output**
	U2C0_DOUT	O3	St/B	**USIC2 Channel 0 Shift Data Output**
	AD5	OH / IH	St/B	**External Bus Interface Address/Data Line 5**
	U0C1_DX1B	I	St/B	**USIC0 Channel 1 Shift Clock Input**
71	P0.6	O0 / I	St/B	**Bit 6 of Port 0, General Purpose Input/Output**
	U1C1_DOUT	O1	St/B	**USIC1 Channel 1 Shift Data Output**
	TxDC1	O2	St/B	**CAN Node 1 Transmit Data Output**
	CCU61_COU T63	O3	St/B	**CCU61 Channel 3 Output**
	A6	OH	St/B	**External Bus Interface Address Line 6**
	U1C1_DX0A	I	St/B	**USIC1 Channel 1 Shift Data Input**
	CCU61_CTR APA	I	St/B	**CCU61 Emergency Trap Input**
	U1C1_DX1B	I	St/B	**USIC1 Channel 1 Shift Clock Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
72	P10.6	O0 / I	St/B	**Bit 6 of Port 10, General Purpose Input/Output**
	U0C0_DOUT	O1	St/B	**USIC0 Channel 0 Shift Data Output**
	TxDC4	O2	St/B	**CAN Node 4 Transmit Data Output**
	U1C0_SELO 0	O3	St/B	**USIC1 Channel 0 Select/Control 0 Output**
	AD6	OH / IH	St/B	**External Bus Interface Address/Data Line 6**
	U0C0_DX0C	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U1C0_DX2D	I	St/B	**USIC1 Channel 0 Shift Control Input**
	CCU60_CTR APA	I	St/B	**CCU60 Emergency Trap Input**
73	P10.7	O0 / I	St/B	**Bit 7 of Port 10, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	CCU60_COU T63	O2	St/B	**CCU60 Channel 3 Output**
	AD7	OH / IH	St/B	**External Bus Interface Address/Data Line 7**
	U0C1_DX0B	I	St/B	**USIC0 Channel 1 Shift Data Input**
	CCU60_CCP OS0A	I	St/B	**CCU60 Position Input 0**
	RxDC4C	I	St/B	**CAN Node 4 Receive Data Input**
	T4INB	I	St/B	**GPT12E Timer T4 Count/Gate Input**
74	P0.7	O0 / I	St/B	**Bit 7 of Port 0, General Purpose Input/Output**
	U1C1_DOUT	O1	St/B	**USIC1 Channel 1 Shift Data Output**
	U1C0_SELO 3	O2	St/B	**USIC1 Channel 0 Select/Control 3 Output**
	TxDC3	O3	St/B	**CAN Node 3 Transmit Data Output**
	A7	OH	St/B	**External Bus Interface Address Line 7**
	U1C1_DX0B	I	St/B	**USIC1 Channel 1 Shift Data Input**
	CCU61_CTR APB	I	St/B	**CCU61 Emergency Trap Input**

Up to 16 Kbytes of on-chip Data SRAM (DSRAM) are used for storage of general user data. The DSRAM is accessed via a separate interface and is optimized for data access.

Note: The actual size of the DSRAM depends on the quoted device type.

2 Kbytes of on-chip Dual-Port RAM (DPRAM) provide storage for user-defined variables, for the system stack, and for general purpose register banks. A register bank can consist of up to 16 word-wide (R0 to R15) and/or byte-wide (RL0, RH0, …, RL7, RH7) General Purpose Registers (GPRs).
The upper 256 bytes of the DPRAM are directly bit addressable. When used by a GPR, any location in the DPRAM is bit addressable.

8 Kbytes of on-chip Stand-By SRAM (SBRAM) provide storage for system-relevant user data that must be preserved while the major part of the device is powered down. The SBRAM is accessed via a specific interface and is powered in domain M.

1024 bytes (2 × 512 bytes) of the address space are reserved for the Special Function Register areas (SFR space and ESFR space). SFRs are word-wide registers which are used to control and monitor functions of the different on-chip units. Unused SFR addresses are reserved for future members of the XC2000 Family. In order to ensure upward compatibility they should either not be accessed or written with zeros.

In order to meet the requirements of designs where more memory is required than is available on chip, up to 12 Mbytes (approximately, see **Table 8**) of external RAM and/or ROM can be connected to the microcontroller. The External Bus Interface also provides access to external peripherals.

The on-chip Flash memory stores code, constant data, and control data. The 320 Kbytes of on-chip Flash memory consist of 1 module of 64 Kbytes (preferably for data storage) and 1 module of 256 Kbytes. Each module is organized in 4-Kbyte sectors. The uppermost 4-Kbyte sector of segment 0 (located in Flash module 0) is used internally to store operation control parameters and protection information.

Note: The actual size of the Flash memory depends on the chosen device type.

Each sector can be separately write protected[1)], erased and programmed (in blocks of 128 Bytes). The complete Flash area can be read-protected. A user-defined password sequence temporarily unlocks protected areas. The Flash modules combine 128-bit read access with protected and efficient writing algorithms for programming and erasing. Dynamic error correction provides extremely high read data security for all read access operations. Access to different Flash modules can be executed in parallel.
For Flash parameters, please see **Section 4.6**.

1) To save control bits, sectors are clustered for protection purposes, they remain separate for programming/erasing.

3.2 External Bus Controller

All external memory access operations are performed by a special on-chip External Bus Controller (EBC). The EBC also controls access to resources connected to the on-chip LXBus (MultiCAN and the USIC modules). The LXBus is an internal representation of the external bus that allows access to integrated peripherals and modules in the same way as to external components.

The EBC can be programmed either to Single Chip Mode, when no external memory is required, or to an external bus mode with the following selections[1]:

- Address Bus Width with a range of 0 … 24-bit
- Data Bus Width 8-bit or 16-bit
- Bus Operation Multiplexed or Demultiplexed

The bus interface uses Port 10 and Port 2 for addresses and data. In the demultiplexed bus modes, the lower addresses are output separately on Port 0 and Port 1. The number of active segment address lines is selectable, restricting the external address space to 8 Mbytes … 64 Kbytes. This is required when interface lines shall be assigned to Port 2.

External $\overline{CS}$ signals (address windows plus default) can be generated and output on Port 4 in order to save external glue logic. External modules can be directly connected to the common address/data bus and their individual select lines.

Important timing characteristics of the external bus interface are programmable (with registers TCONCSx/FCONCSx) to allow the user to adapt it to a wide range of different types of memories and external peripherals.
Access to very slow memories or modules with varying access times is supported by a special ‘Ready’ function. The active level of the control input signal is selectable.

In addition, up to four independent address windows may be defined (using registers ADDRSELx) to control access to resources with different bus characteristics. These address windows are arranged hierarchically where window 4 overrides window 3, and window 2 overrides window 1. All accesses to locations not covered by these four address windows are controlled by TCONCS0/FCONCS0. The currently active window can generate a chip select signal.

The external bus timing is based on the rising edge of the reference clock output CLKOUT. The external bus protocol is compatible with that of the standard C166 Family.

1) Bus modes are switched dynamically if several address windows with different mode settings are used.

3.6 Interrupt System

The architecture of the XC226xN supports several mechanisms for fast and flexible response to service requests; these can be generated from various sources internal or external to the microcontroller. Any of these interrupt requests can be programmed to be serviced by the Interrupt Controller or by the Peripheral Event Controller (PEC).

Using a standard interrupt service the current program execution is suspended and a branch to the interrupt vector table is performed. With the PEC just one cycle is 'stolen' from the current CPU activity to perform the PEC service. A PEC service implies a single byte or word data transfer between any two memory locations with an additional increment of either the PEC source pointer, the destination pointer, or both. An individual PEC transfer counter is implicitly decremented for each PEC service except when performing in the continuous transfer mode. When this counter reaches zero, a standard interrupt is performed to the corresponding source-related vector location. PEC services are particularly well suited to supporting the transmission or reception of blocks of data. The XC226xN has eight PEC channels, each with fast interrupt-driven data transfer capabilities.

With a minimum interrupt response time of 7/11[1)] CPU clocks, the XC226xN can react quickly to the occurrence of non-deterministic events.

Interrupt Nodes and Source Selection

The interrupt system provides 96 physical nodes with separate control register containing an interrupt request flag, an interrupt enable flag and an interrupt priority bit field. Most interrupt sources are assigned to a dedicated node. A particular subset of interrupt sources shares a set of nodes. The source selection can be programmed using the interrupt source selection (ISSR) registers.

External Request Unit (ERU)

A dedicated External Request Unit (ERU) is provided to route and preprocess selected on-chip peripheral and external interrupt requests. The ERU features 4 programmable input channels with event trigger logic (ETL) a routing matrix and 4 output gating units (OGU). The ETL features rising edge, falling edge, or both edges event detection. The OGU combines the detected interrupt events and provides filtering capabilities depending on a programmable pattern match or miss.

Trap Processing

The XC226xN provides efficient mechanisms to identify and process exceptions or error conditions that arise during run-time, the so-called 'Hardware Traps'. A hardware trap causes an immediate system reaction similar to a standard interrupt service (branching

1) Depending if the jump cache is used or not.

3.11 Real Time Clock

The Real Time Clock (RTC) module of the XC226xN can be clocked with a clock signal selected from internal sources or external sources (pins).

The RTC basically consists of a chain of divider blocks:

- Selectable 32:1 and 8:1 dividers (on - off)
- The reloadable 16-bit timer T14
- The 32-bit RTC timer block (accessible via registers RTCH and RTCL) consisting of:
  - a reloadable 10-bit timer
  - a reloadable 6-bit timer
  - a reloadable 6-bit timer
  - a reloadable 10-bit timer

All timers count up. Each timer can generate an interrupt request. All requests are combined to a common node request.

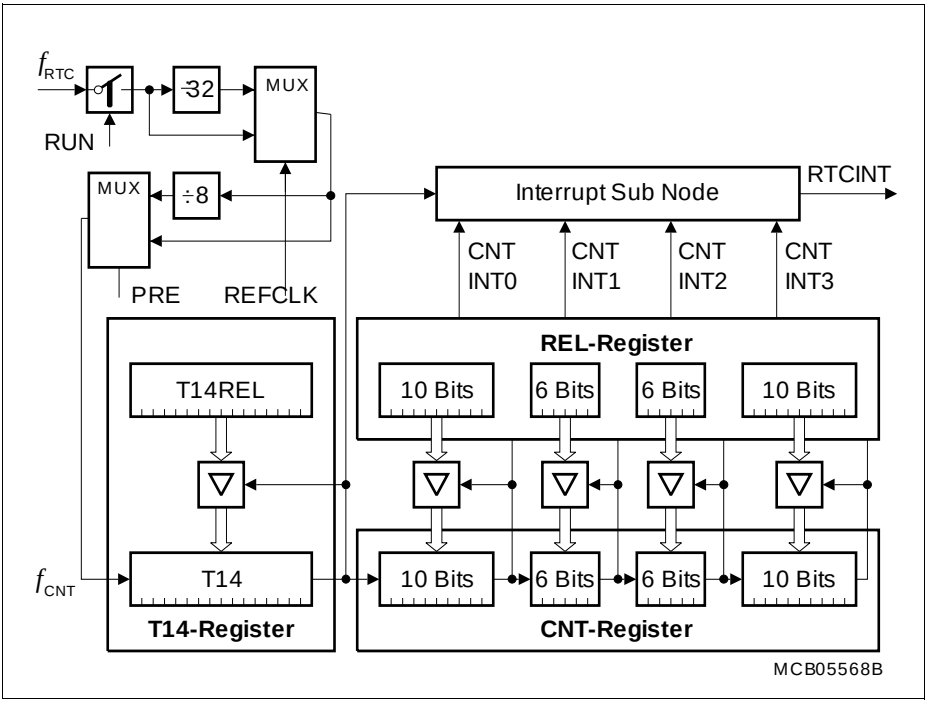

Figure 10 RTC Block Diagram

Note: The registers associated with the RTC are only affected by a power reset.

3.12 A/D Converters

For analog signal measurement, up to two 10-bit A/D converters (ADC0, ADC1) with 11 + 5 multiplexed input channels and a sample and hold circuit have been integrated on-chip. 4 inputs can be converted by both A/D converters. Conversions use the successive approximation method. The sample time (to charge the capacitors) and the conversion time are programmable so that they can be adjusted to the external circuit. The A/D converters can also operate in 8-bit conversion mode, further reducing the conversion time.

Several independent conversion result registers, selectable interrupt requests, and highly flexible conversion sequences provide a high degree of programmability to meet the application requirements. Both modules can be synchronized to allow parallel sampling of two input channels.

For applications that require more analog input channels, external analog multiplexers can be controlled automatically. For applications that require fewer analog input channels, the remaining channel inputs can be used as digital input port pins.

The A/D converters of the XC226xN support two types of request sources which can be triggered by several internal and external events.

- Parallel requests are activated at the same time and then executed in a predefined sequence.
- Queued requests are executed in a user-defined sequence.

In addition, the conversion of a specific channel can be inserted into a running sequence without disturbing that sequence. All requests are arbitrated according to the priority level assigned to them.

Data reduction features reduce the number of required CPU access operations allowing the precise evaluation of analog inputs (high conversion rate) even at a low CPU speed. Result data can be reduced by limit checking or accumulation of results.

The Peripheral Event Controller (PEC) can be used to control the A/D converters or to automatically store conversion results to a table in memory for later evaluation, without requiring the overhead of entering and exiting interrupt routines for each data transfer. Each A/D converter contains eight result registers which can be concatenated to build a result FIFO. Wait-for-read mode can be enabled for each result register to prevent the loss of conversion data.

In order to decouple analog inputs from digital noise and to avoid input trigger noise, those pins used for analog input can be disconnected from the digital input stages. This can be selected for each pin separately with the Port x Digital Input Disable registers.

The Auto-Power-Down feature of the A/D converters minimizes the power consumption when no conversion is in progress.

Broken wire detection for each channel and a multiplexer test mode provide information to verify the proper operation of the analog signal sources (e.g. a sensor system).

3.13 Universal Serial Interface Channel Modules (USIC)

The XC226xN features the USIC modules USIC0, USIC1, USIC2. Each module provides two serial communication channels.

The Universal Serial Interface Channel (USIC) module is based on a generic data shift and data storage structure which is identical for all supported serial communication protocols. Each channel supports complete full-duplex operation with a basic data buffer structure (one transmit buffer and two receive buffer stages). In addition, the data handling software can use FIFOs.

The protocol part (generation of shift clock/data/control signals) is independent of the general part and is handled by protocol-specific preprocessors (PPPs).

The USIC's input/output lines are connected to pins by a pin routing unit. The inputs and outputs of each USIC channel can be assigned to different interface pins, providing great flexibility to the application software. All assignments can be made during runtime.

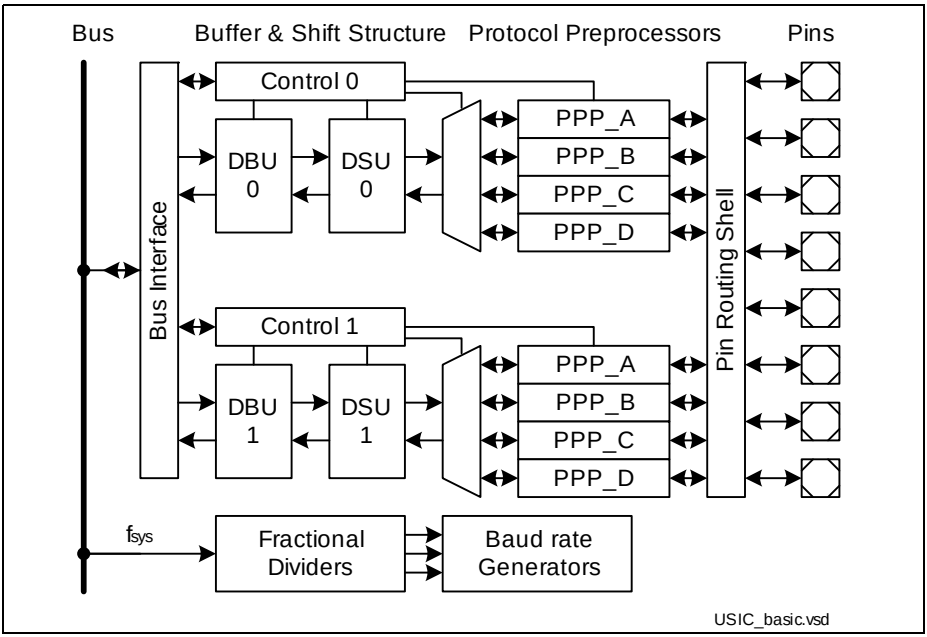

Figure 11 General Structure of a USIC Module

The regular structure of the USIC module brings the following advantages:

- Higher flexibility through configuration with same look-and-feel for data management
- Reduced complexity for low-level drivers serving different protocols
- Wide range of protocols with improved performances (baud rate, buffer handling)

4.3 DC Parameters

These parameters are static or average values that may be exceeded during switching transitions (e.g. output current).

The XC226xN can operate within a wide supply voltage range from 3.0 V to 5.5 V. However, during operation this supply voltage must remain within 10 percent of the selected nominal supply voltage. It cannot vary across the full operating voltage range.

Because of the supply voltage restriction and because electrical behavior depends on the supply voltage, the parameters are specified separately for the upper and the lower voltage range.

During operation, the supply voltages may only change with a maximum speed of dV/dt < 1 V/ms.

Leakage current is strongly dependent on the operating temperature and the voltage level at the respective pin. The maximum values in the following tables apply under worst case conditions, i.e. maximum temperature and an input level equal to the supply voltage.
The value for the leakage current in an application can be determined by using the respective leakage derating formula (see tables) with values from that application.

The pads of the XC226xN are designed to operate in various driver modes. The DC parameter specifications refer to the pad current limits specified in **Section 4.7.4**.

2) Flash module 1 can be erased/programmed while code is executed and/or data is read from Flash module 0.
3) Value of IMB_IMBCTRL.WSFLASH.
4) Programming and erase times depend on the internal Flash clock source. The control state machine needs a few system clock cycles. This increases the stated durations noticably only at extremely low system clock frequencies.

Access to the XC226xN Flash modules is controlled by the IMB. Built-in prefetch mechanisms optimize the performance for sequential access.

Flash access waitstates only affect non-sequential access. Due to prefetch mechanisms, the performance for sequential access (depending on the software structure) is only partially influenced by waitstates.

The timing in the AC Characteristics refers to TCSs. Timing must be calculated using the minimum TCS possible under the given circumstances.
The actual minimum value for TCS depends on the jitter of the PLL. Because the PLL is constantly adjusting its output frequency to correspond to the input frequency (from crystal or oscillator), the accumulated jitter is limited. This means that the relative deviation for periods of more than one TCS is lower than for a single TCS (see formulas and **Figure 20**).

This is especially important for bus cycles using waitstates and for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is negligible.

The value of the accumulated PLL jitter depends on the number of consecutive VCO output cycles within the respective timeframe. The VCO output clock is divided by the output prescaler K2 to generate the system clock signal f_{SYS}. The number of VCO cycles is K2 × **T**, where **T** is the number of consecutive f_{SYS} cycles (TCS).

The maximum accumulated jitter (long-term jitter) D_{Tmax} is defined by:

D_{Tmax} [ns] = ±(220 / (K2 × f_{SYS}) + 4.3)

This maximum value is applicable, if either the number of clock cycles T > (f_{SYS} / 1.2) or the prescaler value K2 > 17.

In all other cases for a timeframe of **T** × TCS the accumulated jitter D_T is determined by:

D_T [ns] = D_{Tmax} × [(1 - 0.058 × K2) × (T - 1) / (0.83 × f_{SYS} - 1) + 0.058 × K2]

f_{SYS} in [MHz] in all formulas.

Example, for a period of 3 TCSs @ 33 MHz and K2 = 4:

D_{max} = ±(220 / (4 × 33) + 4.3) = 5.97 ns (Not applicable directly in this case!)

D_3 = 5.97 × [(1 - 0.058 × 4) × (3 - 1) / (0.83 × 33 - 1) + 0.058 × 4]
= 5.97 × [0.768 × 2 / 26.39 + 0.232]
= 1.7 ns

Example, for a period of 3 TCSs @ 33 MHz and K2 = 2:

D_{max} = ±(220 / (2 × 33) + 4.3) = 7.63 ns (Not applicable directly in this case!)

D_3 = 7.63 × [(1 - 0.058 × 2) × (3 - 1) / (0.83 × 33 - 1) + 0.058 × 2]
= 7.63 × [0.884 × 2 / 26.39 + 0.116]
= 1.4 ns

Table 32 External Bus Timing for Upper Voltage Range (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Address output valid delay for AD15 ... AD0 (MUX mode)	t_{13} CC	–	8	15	ns	
Output valid delay for $\overline{CS}$	t_{14} CC	–	7	13	ns	
Data output valid delay for AD15 ... AD0 (write data, MUX mode)	t_{15} CC	–	8	15	ns	
Data output valid delay for D15 ... D0 (write data, DEMUX mode)	t_{16} CC	–	8	15	ns	
Output hold time for $\overline{RD}$, $\overline{WR}$($\overline{L}$/$\overline{H}$)	t_{20} CC	-2	6	8	ns	
Output hold time for $\overline{BHE}$, ALE	t_{21} CC	-2	6	10	ns	
Address output hold time for AD15 ... AD0	t_{23} CC	-3	6	8	ns	
Output hold time for $\overline{CS}$	t_{24} CC	-3	6	11	ns	
Data output hold time for D15 ... D0 and AD15 ... AD0	t_{25} CC	-3	6	8	ns	
Input setup time for READY, D15 ... D0, AD15 ... AD0	t_{30} SR	25	15	–	ns	
Input hold time READY, D15 ... D0, AD15 ... AD0[1)]	t_{31} SR	0	-7	–	ns	

1) Read data are latched with the same internal clock edge that triggers the address change and the rising edge of RD. Address changes before the end of RD have no impact on (demultiplexed) read cycles. Read data can change after the rising edge of RD.

Table 33 is valid under the following conditions: C_L= 20 pF; voltage_range= lower ; voltage_range= lower

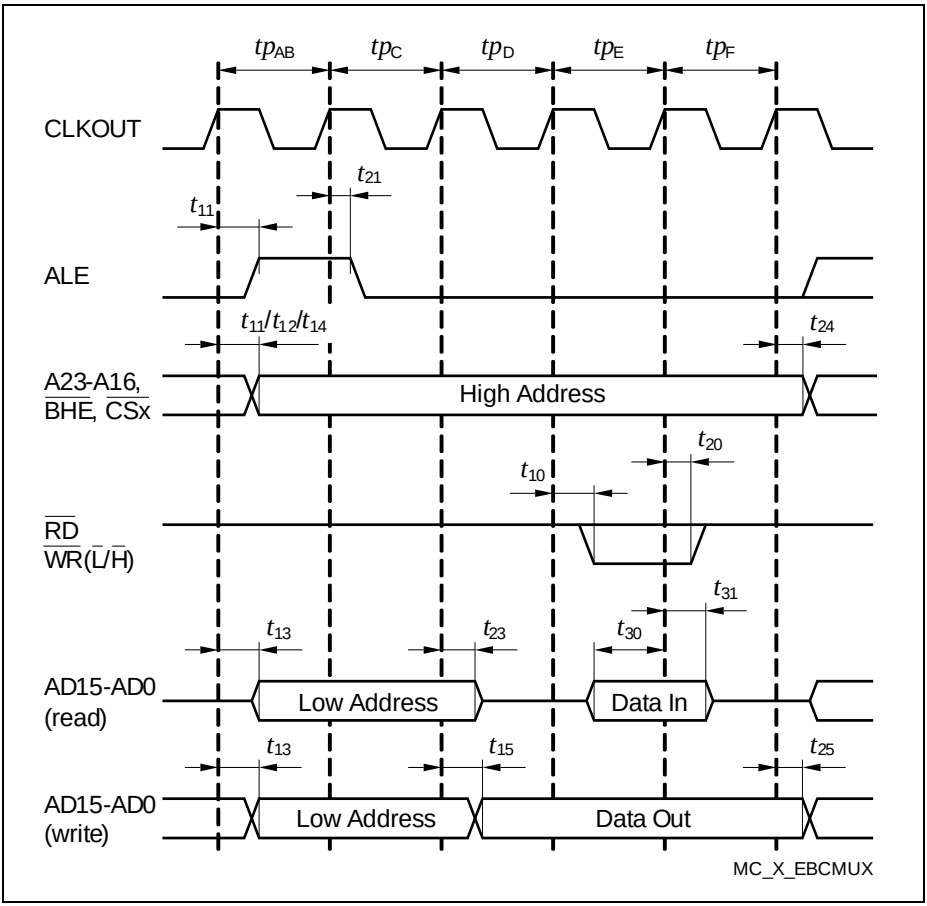

Figure 23 Multiplexed Bus Cycle

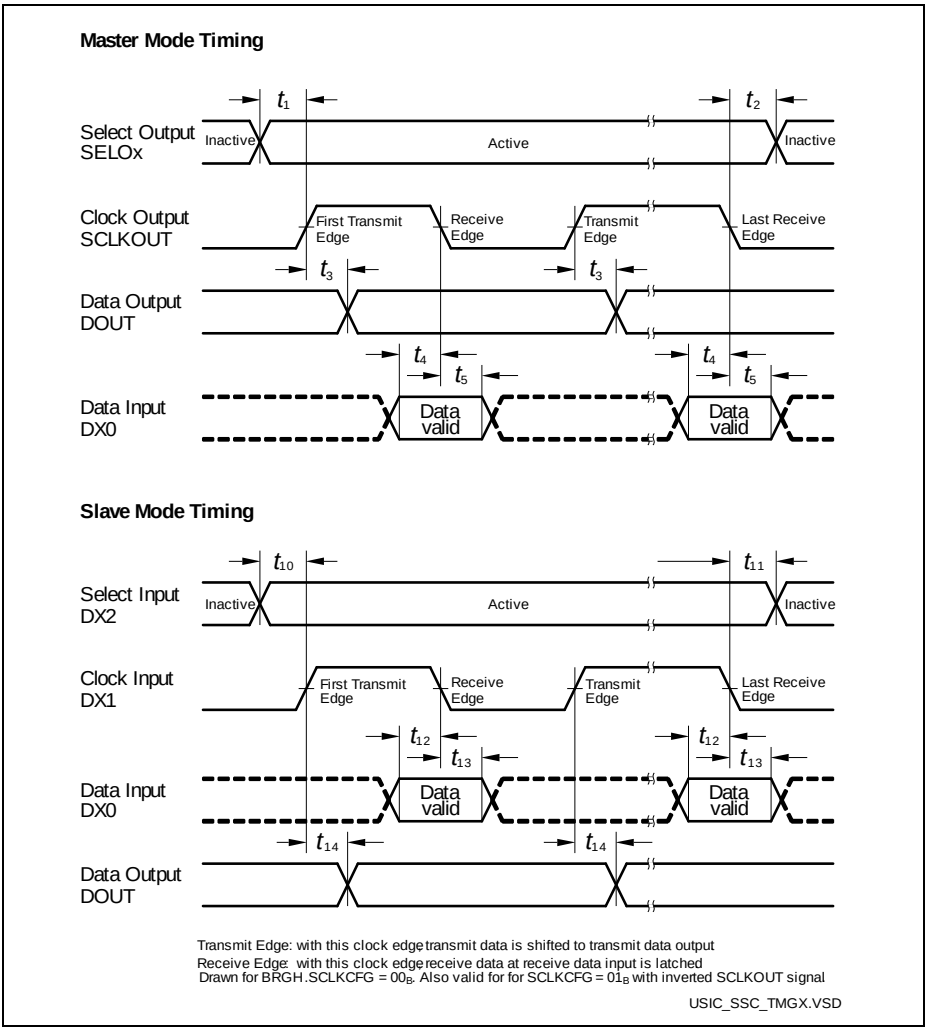

Figure 26 USIC - SSC Master/Slave Mode Timing

Note: This timing diagram shows a standard configuration where the slave select signal is low-active and the serial clock signal is not shifted and not inverted.

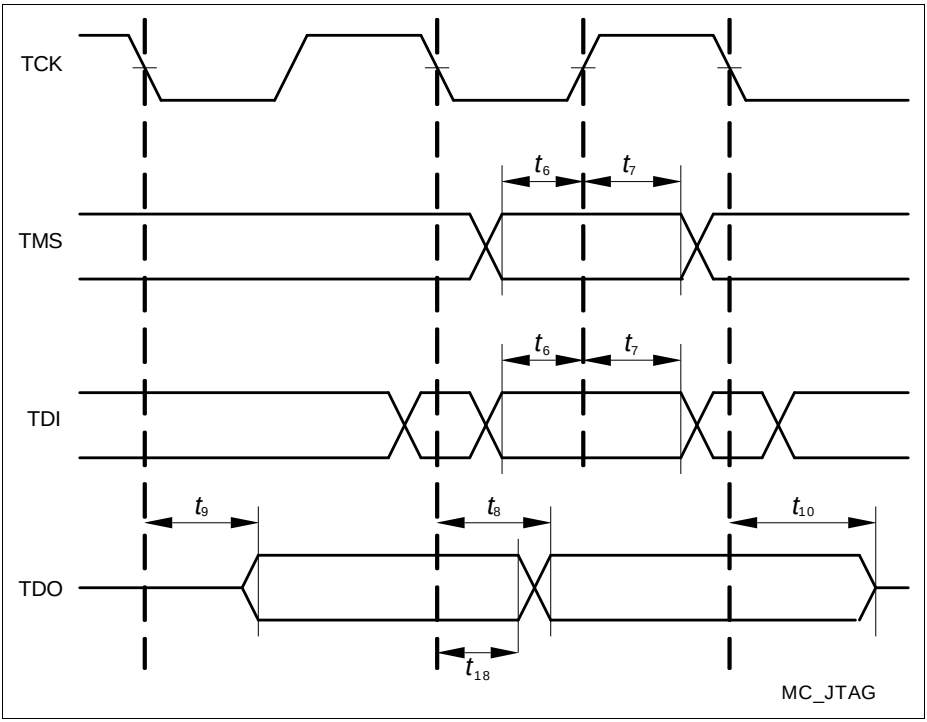

Figure 31 JTAG Timing

5 Package and Reliability

The XC2000 Family devices use the package type PG-LQFP (Plastic Green - Low Profile Quad Flat Package). The following specifications must be regarded to ensure proper integration of the XC226xN in its target environment.

5.1 Packaging

These parameters specify the packaging rather than the silicon.

Table 42 Package Parameters (PG-LQFP-100-8/-15)

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Exposed Pad Dimension	Ex × Ey	–	5.2 × 5.2	mm	–
Power Dissipation	P_{DISS}	–	0.8	W	–
Thermal resistance Junction-Ambient	$R_{\Theta JA}$	–	54	K/W	No thermal via[1)]
			49	K/W	4-layer, no pad[2)]
			27	K/W	4-layer, pad[3)]

1) Device mounted on a 4-layer board without thermal vias; exposed pad not soldered.

2) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad not soldered.

3) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad soldered to the board.

Note: To improve the EMC behavior, it is recommended to connect the exposed pad to the board ground, independent of the thermal requirements.
Board layout examples are given in an application note.

Package Compatibility Considerations

The XC226xN is a member of the XC2000 Family of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the Exposed Pad (if present) may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.